



US Department of Commerce
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042390.P1674C2D4

Application No.:
09/707,486

Applicant:
Pippin, J.

Filing Date:
November 7, 2000

US Patent Documents

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Examiner

M. Shoshit

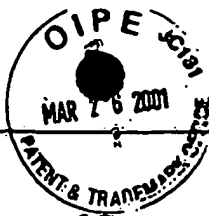
Date Considered

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| US Department of Commerce Patent and Trademark Office | | Atty. Docket No.: 042390.P1674C2D4 | | Application No.: 09/707,486 | | |
| | | Applicant: Pippin, J. | | | | |
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